

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: **03057295 A**

(43) Date of publication of application: **12.03.91**

(51) Int. Cl.

**H05K 3/34**

(21) Application number: **01191536**

(71) Applicant: **FUJITSU LTD**

(22) Date of filing: **26.07.89**

(72) Inventor: **OKADA HIROYUKI**

(54) **METHOD OF MOUNTING ELECTRONIC COMPONENTS ON DOUBLE-SIDED MOUNTING BOARD**

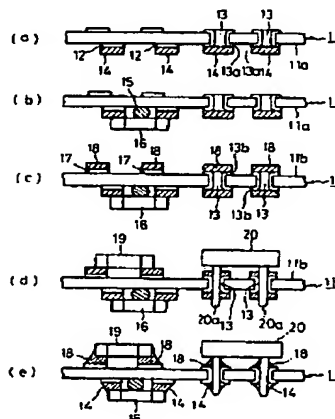
solder cream 14 and 18 may be melted so as to solder each component.

COPYRIGHT: (C)1991,JPO&Japio

(57) Abstract:

PURPOSE: To make it possible to solder components mounted on the surface of a printed board on both sides and a dip component simultaneously by applying solder cream on a soldered section of said component mounted on the surface of said printed board and a land section on a through hole for mounting a dip component simultaneously.

CONSTITUTION: A soldered section 12 of a components mounted on the surface of a printed board 11 on one side 11a and a land section 13a, which is one party of a dip component mounting through hole 13, are coated with solder cream 14 based on screen printing, using a metal mask. Then, a surface mounted component 16 is bonded on one side 11a of the printed board 11 in a specified position, using a bonding agent. Solder cream 18 is applied on a land section 13b, which is one party of the through hole 13 based on screen printing, using a metal mask. In succession, a surface mounted component 19 and a dip component 20 are installed to the other side 11b of the printed board 11 in a specified position. The printed board 11 is heated in a heating furnace so that



BEST AVAILABLE COPY